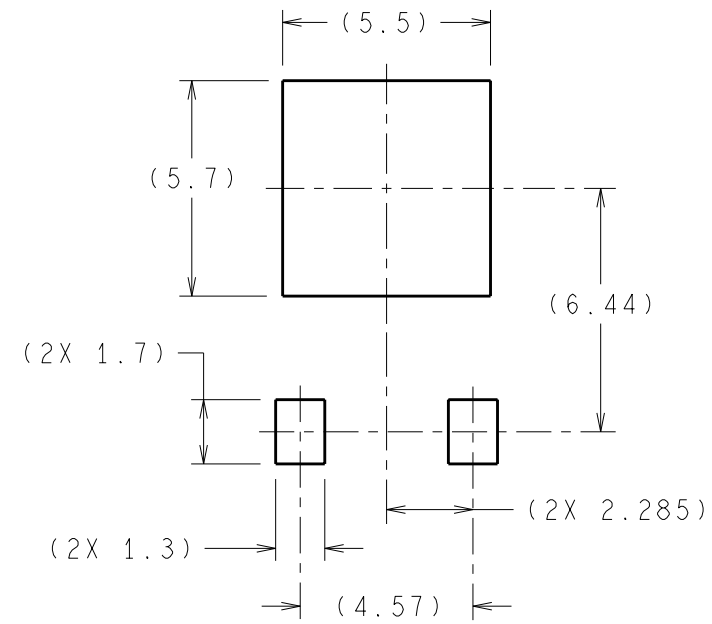
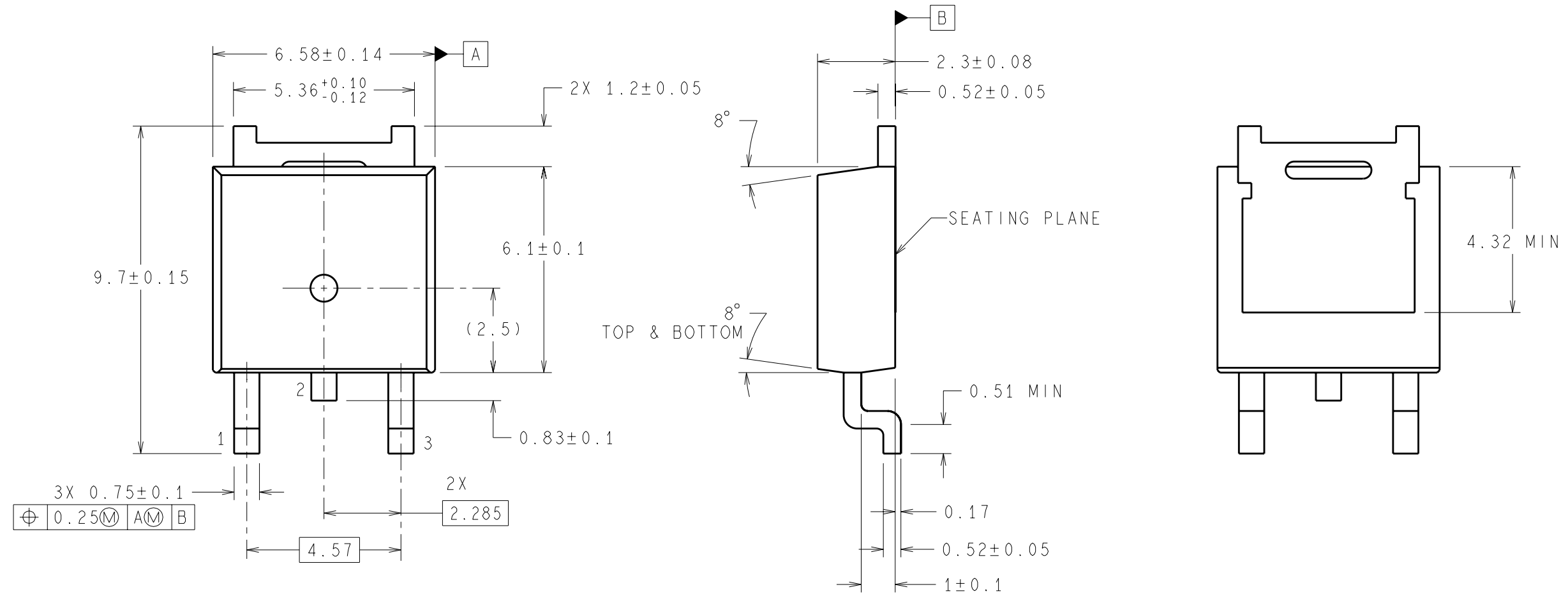


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12120	10/23/1998	NOR/MS/SH
B	ADD LAND PATTERN RECOMMENDATION VIEW; DIM 2.285 WAS 2.28	12261	06/30/1999	MS/PS
C	UPDATE DWG PER CURRENT STD'S; REVISE NOTE 1; UPDATE NOTE 2; CHANGE TO B SIZE DWG FORMAT.	1015	04/29/2003	MS/RW
D	LAND PATT: DIM (6.44) WAS (7.4); REMOVE DIM (11.1)	2696	02/02/2009	TL/RW



DIMENSIONS ARE IN MILLIMETERS

LAND PATTERN RECOMMENDATION



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- REFERENCE JEDEC REGISTRATION TO-252, VARIATION AA.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	TO-252, MOLDED, JEDEC, 6.58x6.1x2.3mm, 3 LD, 2.28mm PITCH, S/M	
DRAWN	NOR AR	10/23/1998			
DFTG. CHK.	<i>KURT SINCERBOX</i>	02/02/2009			
ENGR. CHK.	<i>RANDALL WALBERG</i>	02/02/2009			
 PROJECTION MM		SCALE	SIZE	DRAWING NUMBER	REV
		NTS	B	(SC)MKT-TD03B	D
FORMERLY: N/A		SHEET 1 of 1			